

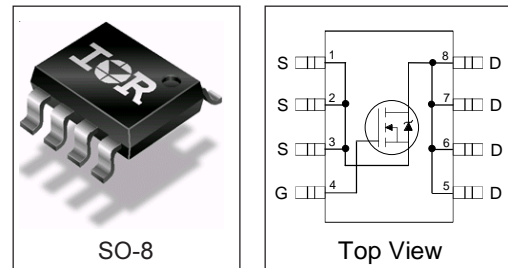
- N-Channel Application-Specific MOSFETs
- Ideal for CPU Core DC-DC Converters
- Low Conduction Losses
- Low Switching Losses
- Minimizes Parallel MOSFETs for high current applications
- 100% R<sub>G</sub> Tested

**Description**

This new device employs advanced HEXFET Power MOSFET technology to achieve an unprecedented balance of on-resistance and gate charge. The reduced conduction and switching losses make it ideal for high efficiency DC-DC converters that power the latest generation of microprocessors.

The IRF7811AV has been optimized for all parameters that are critical in synchronous buck converters including R<sub>DS(on)</sub>, gate charge and Cdv/dt-induced turn-on immunity. The IRF7811AV offers an extremely low combination of Q<sub>sw</sub> & R<sub>DS(on)</sub> for reduced losses in both control and synchronous FET applications.

The package is designed for vapor phase, infra-red, convection, or wave soldering techniques. Power dissipation of greater than 2W is possible in a typical PCB mount application.



**DEVICE CHARACTERISTICS** ⑤

|                     | <b>IRF7811AV</b> |
|---------------------|------------------|
| R <sub>DS(on)</sub> | 11 mΩ            |
| Q <sub>G</sub>      | 17 nC            |
| Q <sub>SW</sub>     | 6.7 nC           |
| Q <sub>OSS</sub>    | 8.1 nC           |

**Absolute Maximum Ratings**

| Parameter   | Symbol                            | IRF7811AV             | Units |
|---|-----------------------------------|-----------------------|-------|
| Drain-to-Source Voltage                               | V <sub>DS</sub>                   | 30                    | V     |
| Gate-to-Source Voltage                                | V <sub>GS</sub>                   | ±20                   |       |
| Continuous Output Current<br>(V <sub>GS</sub> ≥ 4.5V) | I <sub>D</sub>                    | T <sub>A</sub> = 25°C | 10.8  |
|   |                                   | T <sub>L</sub> = 90°C | 11.8  |
| Pulsed Drain Current ①                                | I <sub>DM</sub>                   | 100                   |       |
| Power Dissipation ③                                   | P <sub>D</sub>                    | T <sub>A</sub> = 25°C | 2.5   |
|   |                                   | T <sub>L</sub> = 90°C | 3.0   |
| Junction & Storage Temperature Range                  | T <sub>J</sub> , T <sub>STG</sub> | -55 to 150            | °C    |
| Continuous Source Current (Body Diode)                | I <sub>S</sub>                    | 2.5                   | A     |
| Pulsed Source Current ①                               | I <sub>SM</sub>                   | 50                    |       |

**Thermal Resistance**

| Parameter                       | Symbol           | Typ | Max | Units |
|---------------------------------|------------------|-----|-----|-------|
| Maximum Junction-to-Ambient ③ ⑥ | R <sub>θJA</sub> | —   | 50  | °C/W  |
| Maximum Junction-to-Lead ⑥      | R <sub>θJL</sub> | —   | 20  |       |

## Electrical Characteristics

| Parameter                                  | Symbol        | Min | Typ  | Max       | Units      | Conditions   |
|--|---------------|-----|------|-----------|------------|--|
| Drain-to-Source Breakdown Voltage          | $V_{(BR)DSS}$ | 30  | —    | —         | V          | $V_{GS} = 0V, I_D = 250\mu A$  |
| Static Drain-to-Source On-Resistance       | $R_{DS(on)}$  | —   | 11   | 14        | m $\Omega$ | $V_{GS} = 4.5V, I_D = 15A$ ②   |
| Gate Threshold Voltage                     | $V_{GS(th)}$  | 1.0 | —    | 3.0       | V          | $V_{DS} = V_{GS}, I_D = 250\mu A$  |
| Drain-to-Source Leakage Current            | $I_{DSS}$     | —   | —    | 50        | $\mu A$    | $V_{DS} = 30V, V_{GS} = 0V$  |
|  |               | —   | —    | 20        | $\mu A$    | $V_{DS} = 24V, V_{GS} = 0V$  |
|  |               | —   | —    | 100       | mA         | $V_{DS} = 24V, V_{GS} = 0V, T_J = 100^\circ C$   |
| Gate-to-Source Leakage Current             | $I_{GSS}$     | —   | —    | $\pm 100$ | nA         | $V_{GS} = \pm 20V$   |
| Total Gate Charge, Control FET             | $Q_g$         | —   | 17   | 26        | nC         | $V_{DS} = 24V, I_D = 15A, V_{GS} = 5.0V$<br>$V_{GS} = 5.0V, V_{DS} < 100mV$<br>$V_{DS} = 16V, I_D = 15A$ |
| Total Gate Charge, Synch FET               | $Q_g$         | —   | 14   | 21        |            |  |
| Pre-V <sub>th</sub> Gate-to-Source Charge  | $Q_{gs1}$     | —   | 3.4  | —         |            |  |
| Post-V <sub>th</sub> Gate-to-Source Charge | $Q_{gs2}$     | —   | 1.6  | —         |            |  |
| Gate-to-Drain ("Miller") Charge            | $Q_{gd}$      | —   | 5.1  | —         |            |  |
| Switch Charge ( $Q_{gs2} + Q_{gd}$ )       | $Q_{SW}$      | —   | 6.7  | —         |            |  |
| Output Charge                              | $Q_{OSS}$     | —   | 8.1  | 12        |            |  |
| Gate Resistance                            | $R_G$         | 0.5 | —    | 4.4       | $\Omega$   |  |
| Turn-On Delay Time                         | $t_{d(on)}$   | —   | 8.6  | —         | ns         | $V_{DD} = 16V$<br>$I_D = 15A$<br>$V_{GS} = 5.0V$<br>Clamped Inductive Load                               |
| Rise Time                                  | $t_r$         | —   | 21   | —         |            |  |
| Turn-Off Delay Time                        | $t_{d(off)}$  | —   | 43   | —         |            |  |
| Fall Time                                  | $t_f$         | —   | 10   | —         |            |  |
| Input Capacitance                          | $C_{iss}$     | —   | 1801 | —         | pF         | $V_{GS} = 0V$<br>$V_{DS} = 10V$  |
| Output Capacitance                         | $C_{oss}$     | —   | 723  | —         |            |  |
| Reverse Transfer Capacitance               | $C_{rss}$     | —   | 46   | —         |            |  |

## Diode Characteristics

| Parameter   | Symbol   | Min | Typ | Max | Units | Conditions  |
|---|----------|-----|-----|-----|-------|---|
| Diode Forward Voltage                               | $V_{SD}$ | —   | —   | 1.3 | V     | $T_J = 25^\circ C, I_S = 15A$ ②, $V_{GS} = 0V$                                  |
| Reverse Recovery Charge ④                           | $Q_{rr}$ | —   | 50  | —   | nC    | $di/dt = 700A/\mu s$<br>$V_{DD} = 16V, V_{GS} = 0V, I_D = 15A$                  |
| Reverse Recovery Charge (with Parallel Schottsky) ④ | $Q_{rr}$ | —   | 43  | —   | nC    | $di/dt = 700A/\mu s$ , (with 10BQ040)<br>$V_{DD} = 16V, V_{GS} = 0V, I_D = 15A$ |

### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Pulse width  $\leq 400 \mu s$ ; duty cycle  $\leq 2\%$ .
- ③ When mounted on 1 inch square copper board,  $t < 10$  sec.
- ④ Typ = measured -  $Q_{oss}$
- ⑤ Typical values of  $R_{DS(on)}$  measured at  $V_{GS} = 4.5V$ ,  $Q_g$ ,  $Q_{SW}$  and  $Q_{OSS}$  measured at  $V_{GS} = 5.0V$ ,  $I_F = 15A$ .
- ⑥  $R_{\theta}$  is measured at  $T_J$  approximately  $90^\circ C$

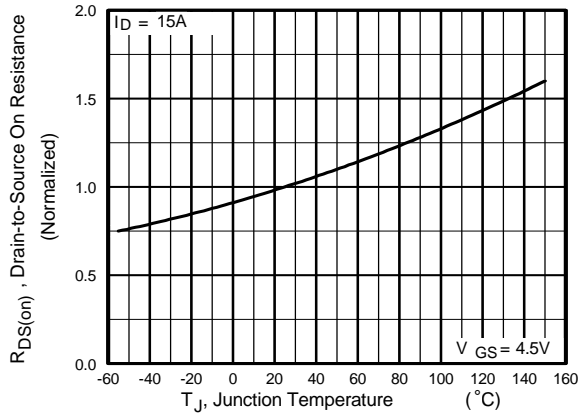


Figure 1. Normalized On-Resistance vs. Temperature

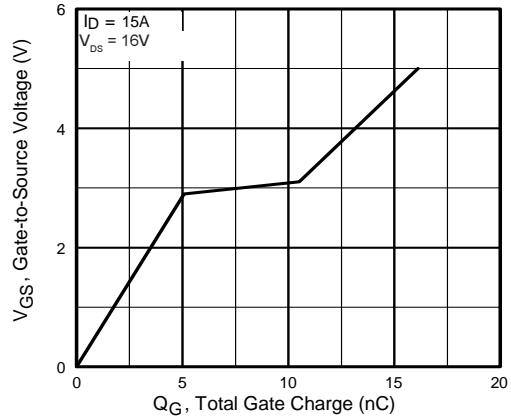


Figure 2. Gate-to-Source Voltage vs. Typical Gate Charge

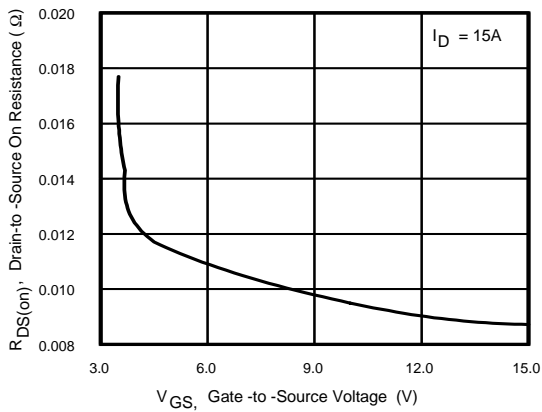


Figure 3. Typical  $R_{DS(on)}$  vs. Gate-to-Source Voltage

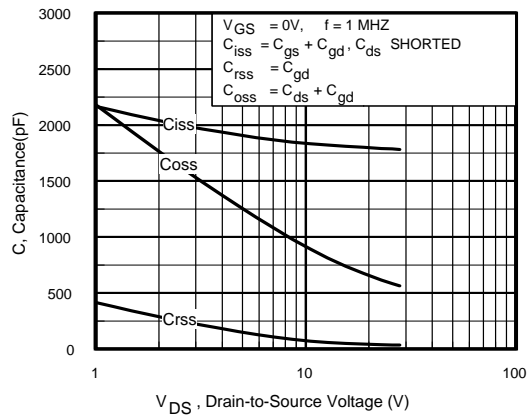


Figure 4. Typical Capacitance vs. Drain-to-Source Voltage

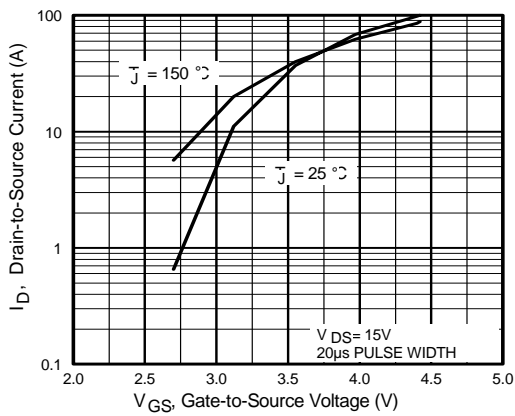


Figure 5. Typical Transfer Characteristics

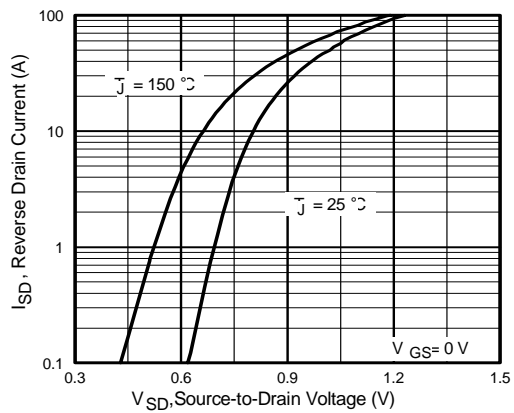


Figure 6. Typical Source-Drain Diode Forward Voltage

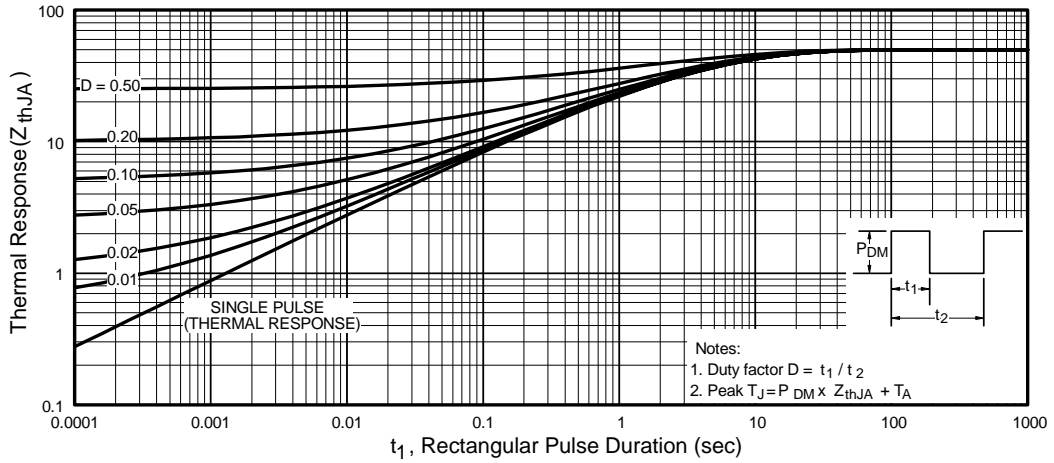


Figure 7. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

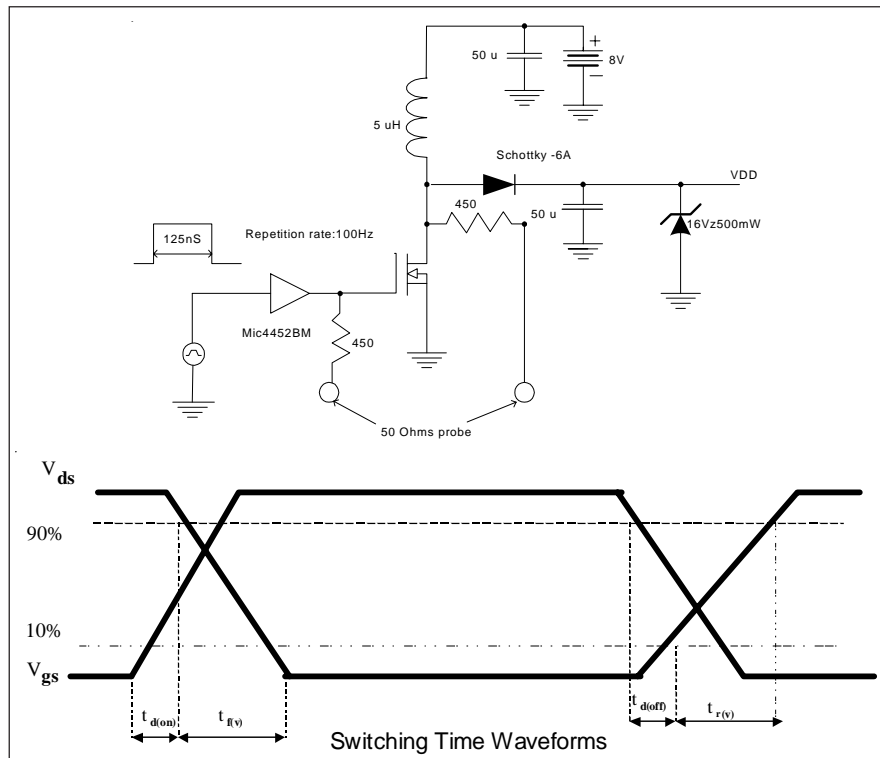
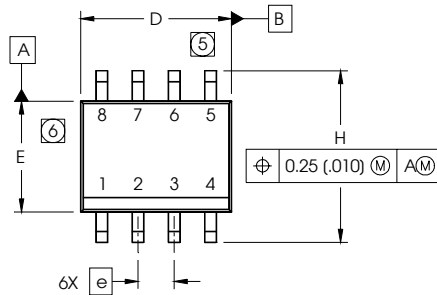
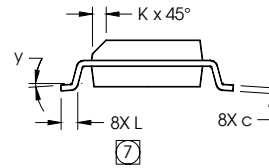
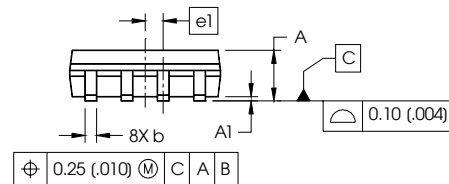


Figure 8. Clamped Inductive load test diagram and switching waveform

## SO-8 Package Details



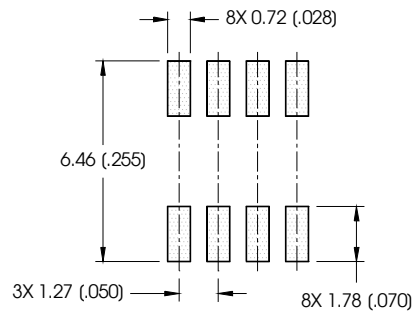
| DIM | INCHES     |       | MILLIMETERS |      |
|-----|------------|-------|-------------|------|
|     | MIN        | MAX   | MIN         | MAX  |
| A   | .0532      | .0688 | 1.35        | 1.75 |
| AI  | .0040      | .0098 | 0.10        | 0.25 |
| b   | .013       | .020  | 0.33        | 0.51 |
| c   | .0075      | .0098 | 0.19        | 0.25 |
| D   | .189       | .1968 | 4.80        | 5.00 |
| E   | .1497      | .1574 | 3.80        | 4.00 |
| e   | .050 BASIC |       | 1.27 BASIC  |      |
| e1  | .025 BASIC |       | 0.635 BASIC |      |
| H   | .2284      | .2440 | 5.80        | 6.20 |
| K   | .0099      | .0196 | 0.25        | 0.50 |
| L   | .016       | .050  | 0.40        | 1.27 |
| y   | 0°         | 8°    | 0°          | 8°   |



**NOTES:**

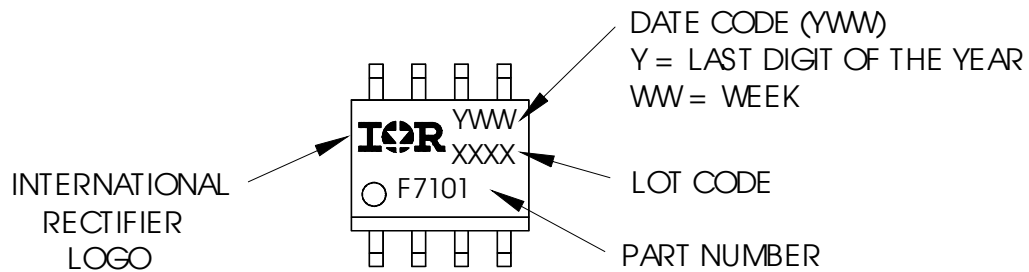
1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER
3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
- ⑤ DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.15 (.006).
- ⑥ DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 (.010).
- ⑦ DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.

**FOOTPRINT**



## SO-8 Part Marking

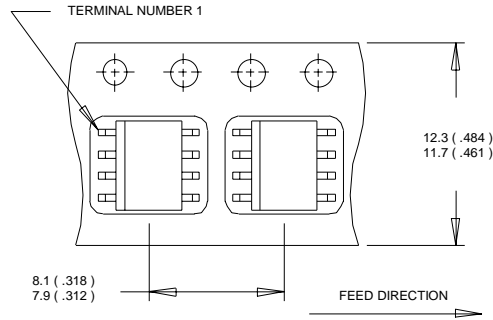
EXAMPLE: THIS IS AN IRF7101 (MOSFET)



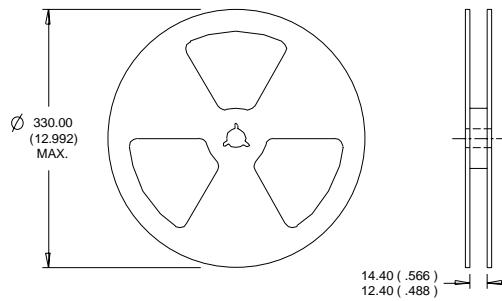
# IRF7811AV

International  
**IR** Rectifier

## SO-8 Tape and Reel



- NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
  2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
  3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



- NOTES :
1. CONTROLLING DIMENSION : MILLIMETER.
  2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Data and specifications subject to change without notice.  
This product has been designed and qualified for the industrial market.  
Qualification Standards can be found on IR's Web site.

International  
**IR** Rectifier

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